

High Performance, Dual Thermal and Visible OEM Camera Module

HADRON™ 640 SERIES



The ITAR-free Hadron 640 series pairs a 64MP visible camera with a performance-leading 640x512 resolution radiometric Boson® or Boson+ thermal camera in a single easy-to-integrate module. With a size, weight, and power (SWaP) optimized design, it is an ideal dual sensor payload for integration into unmanned aircraft systems (UAS), unmanned ground vehicles (UGV), robotic platforms, and emerging AI applications utilizing Teledyne FLIR Prism™ software.

Hadron 640 models share mechanical and electrical interfaces simplifying design. Compatible with Teledyne FLIR's Prism AI detection, tracking, and classification models and Prism ISP libraries for super-resolution, turbulence mitigation, contrast enhancement, and more, Hadron 640 series enables effective AI-based applications. With drivers available for market leading processors from NVIDIA®, Qualcomm®, and more plus industry-leading integration support, Hadron 640 also reduces development cost and shortens time to market.

Evaluate Prism with the Hadron 640R using the Prism Development Kit for Qualcomm RB5 today.



INDUSTRY-LEADING THERMAL AND VISIBLE CAMERA PERFORMANCE

Collect high-speed, VGA radiometric thermal and HD visible imagery.

- AI-ready with Teledyne FLIR Prism AI and ISP
- 64MP visible camera resolution
- Available radiometric, 640x512-resolution Boson+ provides industry leading NETD of ≤ 20 mK
- Flexible dual 60 Hz video output via USB or MIPI

BUILT FOR INTEGRATORS

Reduce development cost and time to market with solution from a single, reliable supplier.

- ITAR-free and classified under US Department of Commerce jurisdiction as ECCN 6A003.b.4.b
- Drivers and sample code available for NVIDIA Jetson Nano, Qualcomm RB5, and more
- Highly qualified, technical services team available to support integration
- Evaluate capabilities with Prism Development Kit for Qualcomm RB5

SIZE, WEIGHT, AND POWER (SWaP) OPTIMIZED DESIGN

Optimize design and operation time with compact, lightweight, and low-power module.

- Low, steady state power consumption at 1.8W
- IP54-rated dust and water protection
- Lightweight 56 g enables longer flight time and extends battery life
- Shared mechanical and electrical interface across all models

For more information visit:
www.flir.com/hadron

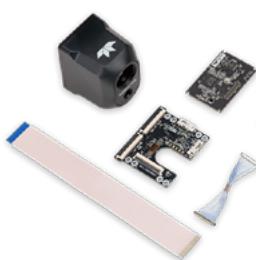
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SPECIFICATIONS

Imaging & Optical			
Thermal Imaging Detector	Boson 640 x 512 pixels, 12 μ m pitch, USB 3.0, 2-lane MIPI	Boson+ 640 x 512 pixels, 12 μ m pitch, USB 3.0, 2-lane MIPI	Boson+ 640 x 512 pixels, 12 μ m pitch, USB 3.0, 2-lane MIPI
Thermal Sensitivity	<40 mK	<20 mK	<20 mK
EO Camera Optics		EFL 4.8mm, 67° HFOV, F/# 1/2.3	
EO Camera Sensor		9248 x 6944 pixels (64.2 MP), 0.7 μ m pitch, 4-lane MIPI	
EO Camera Video		Full resolution @ 60Hz	
Aspect Ratio, Visible		4 to 3	
IMU		ICM20602, I2C or SPI (selectable)	
IR Camera Optics		EFL 13.6mm, 32° HFOV, F/# 1.0	
IR Camera Video		Full resolution @ 60Hz	
Aspect Ratio, Thermal		5 to 4	
Radiometry			
Temperature Accuracy	± 5 °C or less, over 0 °C to 100 °C range	Non-Radiometric	± 5 °C or less, over 0 °C to 100 °C range
Electrical			
Electrical Interface		Hirose DF40C-50DP-0.4V(51) Example of mating connector: DF40HC(2.5)-50DS-0.4V(51)	
Power		5V supply voltage. Typical power dissipation < 1800mW, Max < 2900mW	
Mechanical			
Mechanical Interface		Screw mount to back plate	
Size [w/o lens]		35 x 49 x 45 mm (1.38" x 1.93" x 1.77")	
Weight		56 g	
Environment & Approvals			
Environmental Sealing		IP54 (with the rear interfaces sealed)	
Operational & Storage Temperature		-20 °C to +60 °C	
Tested EMI Performance		FCC part 15 Class B	
Software			
Software Drivers*		NVIDIA Jetson Nano, Qualcomm Snapdragon RB5, Qualcomm Snapdragon 865 *Contact Teledyne FLIR for latest software drivers	
Ordering			
Part Numbers	70640AS32-6PMRXX	70640AS32-6PAAXP	70640AS32-6PARXP

DEVELOPMENT KITS



NVIDIA Jetson Nano



Qualcomm Snapdragon RB5



Qualcomm Snapdragon 865



Prism Development Kit for Qualcomm RB5

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For the most up-to-date specs, go to www.flir.com/hadron
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